

customer	
pcb name	
WE article number	
engineer	
date	



Multilayer 10 Layers

PCB Thickness : 2,41 mm +/- 10%

Rigid area Structure	Rigid area Thickness	Material description	Via types	Layer usage	Impedance	
					Er	Z[Ohm] Line / Space
Soldermask	15				3,5	
L1	45	* Incl. Plating	Top-Layer			
	230	FR4 TG 150			4,3	
L2	18					
	250	FR4 TG 150			4,3	
L3	18					
	230	FR4 TG 150			4,3	
L4	18					
	250	FR4 TG 150			4,3	
L5	18					
	230	FR4 TG 150			4,3	
L6	18					
	250	FR4 TG 150			4,3	
L7	18					
	230	FR4 TG 150			4,3	
L8	18					
	250	FR4 TG 150			4,3	
L9	18					
	230	FR4 TG 150			4,3	
L10	45	* Incl. Plating	Bottom-Layer			
Soldermask	15				3,5	

Notes:	Via types - Standard and options		
50 % copper occupancy IL			
final copper thickness according to IPC 6012			
Dielectric material according IPC-4101 E / 128 (127)			
For Microvia technology please use our HDI stackups			
Revision: Created: W. Brylka / Scrutinised: A. Schilpp / Approved: A.Schilpp			
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